



Title of Change:	Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belgium related to Fab2 Sale	
Proposed Changed Material First Ship Date:	30 Jun 2022 or earlier if approved by customer	
Current Material Last Order Date:	30 Jun 2021 with flexibility for update at FPCN issue date	
Current Material Last Delivery Date:	12months after FPCN issue date, unless otherwise mutually agreed	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local ON Semiconductor Sales Office or Alicia.Tuckett@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com> . Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Catherine.DeKeukeleire@onsemi.com	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com> .	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor New wafer diameter	
Description and Purpose:		
<p>Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belgium due to Fab2 sale.</p> <p>EOL notice PD23383Z from 7/1/2020 . Decision to transfer as derivative was made later.</p> <p>NCV890430MW33TXG was discontinued, but was later decided to continue with this part with the change per IPCN23658Z.</p> <ul style="list-style-type: none"> PD23383Z issued 7/1/2020: NCV890430MW33TXG (IPCN23658Z will cancel and replace PD23383Z) 		
Wafer fab location	Fab2, Oudenaarde, Belgium (Current Fab)	ON Gresham, Oregon, USA (New Fab)
Wafer Diameter	Substrate: Si (150mm) 6"	Substrate: Si (200mm) 8"
Product marking change		Documented at product level at FPCN issue



Reason / Motivation for Change:	Source/Supply/Capacity Changes	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	<p>The device will be qualified and validated based on the same Product Specification. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Gresham, Oregon USA	None	
ON Semiconductor Oudenaarde, Belgium		
Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode	
Reliability Data Summary:		
Qualification plan is device specific and will be provided upon request		
Electrical Characteristics Summary:		
Electrical characteristics are not impacted.		
List of Affected Parts:		
<p>Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.</p>		
Current Part Number	New Part Number	Qualification Vehicle
NCV890430MW33TXG	NA	NA